

Test Laboratory: Compliance Certification Services
File Name: [ch 384 RC1 SO3 8k Enhanced Low.da4](#)

DUT: HCT Dual Band phone; Type: PN-819; Serial: N/A
Program Name: HAC_TCoil_WD_Emission

Communication System: CDMA; Frequency: 836.52 MHz; Duty Cycle: 1:1

Medium parameters used: $\sigma = 0$ mho/m, $\epsilon_r = 1$; $\rho = 1$ kg/m³

Phantom section: AMB with Coil Section

DASY4 Configuration:

- Probe: AM1DV2 - 1012; ; Calibrated: 4/18/2006
- Sensor-Surface: 0mm (Fix Surface)
- Electronics: DAE4 SN558; Calibrated: 1/20/2006
- Phantom: HAC Test Arch with Coil; Type: SD HAC P01 BA; Serial: 100x
- Measurement SW: DASY4, V4.7 Build 44; Postprocessing SW: SEMCAD, V1.8 Build 171

Scans/z (axial) rough 50 x 50/ABM Interpolated Signal(x,y,z) (61x61x1):

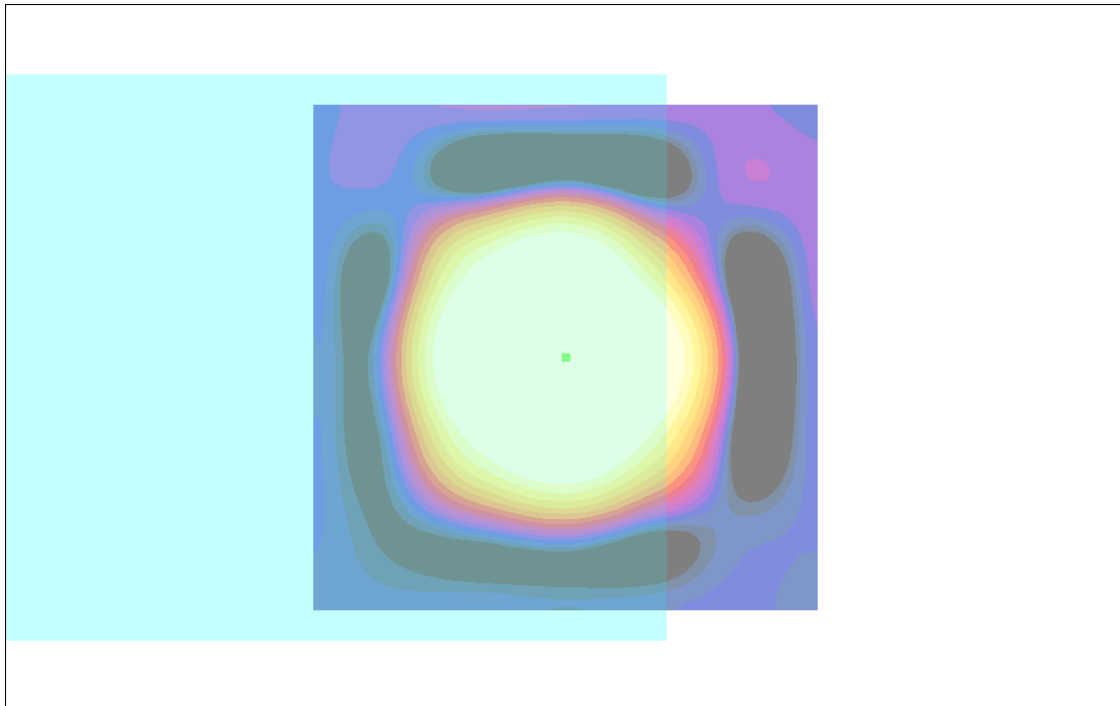
Measurement grid: dx=10mm, dy=10mm

Cursor:

ABM1 = 11.827 dB A/m

BWC Factor = -0.206004 dB

Location: 0, 0, 363.7 mm



0 dB = 1.00A/m

Test Laboratory: Compliance Certification Services

File Name: [ch 384 RC2 SO17 13K Low.da4](#)

DUT: HCT Dual Band phone; Type: PN-819; Serial: N/A

Program Name: HAC_TCoil_WD_Emission

Communication System: CDMA; Frequency: 836.52 MHz; Duty Cycle: 1:1

Medium parameters used: $\sigma = 0$ mho/m, $\epsilon_r = 1$; $\rho = 1$ kg/m³

Phantom section: AMB with Coil Section

DASY4 Configuration:

- Probe: AM1DV2 - 1012; ; Calibrated: 4/18/2006
- Sensor-Surface: 0mm (Fix Surface)
- Electronics: DAE4 SN558; Calibrated: 1/20/2006
- Phantom: HAC Test Arch with Coil; Type: SD HAC P01 BA; Serial: 100x
- Measurement SW: DASY4, V4.7 Build 44; Postprocessing SW: SEMCAD, V1.8 Build 171

Scans/z (axial) rough 50 x 50/ABM Interpolated Signal(x,y,z) (61x61x1):

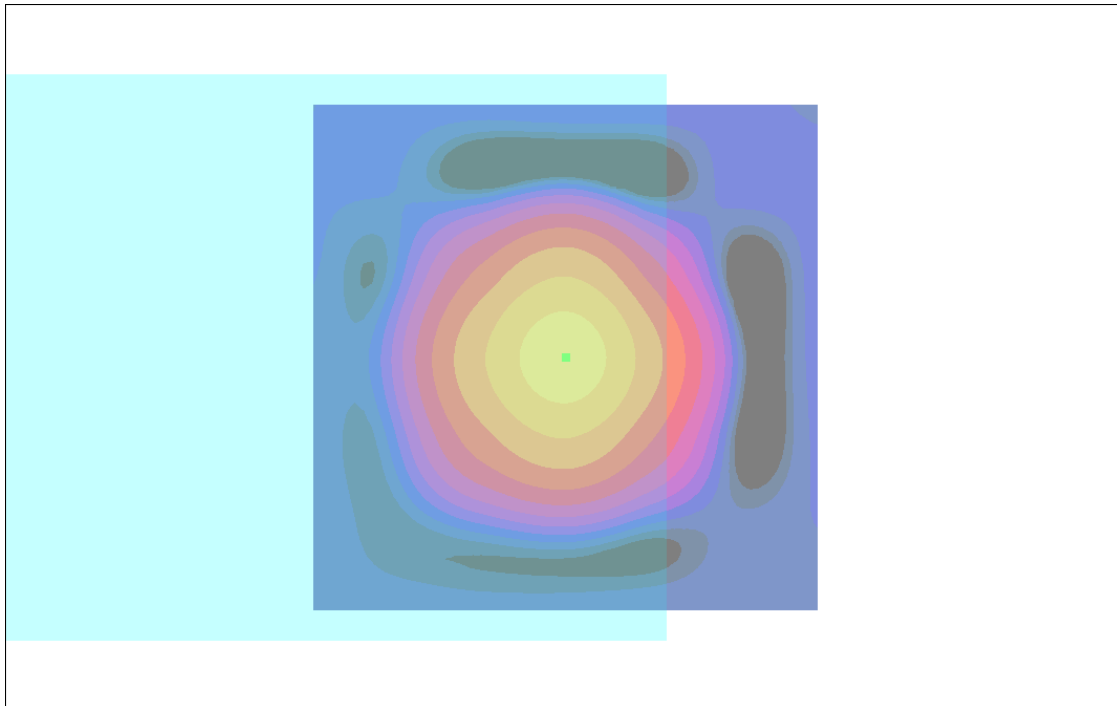
Measurement grid: dx=10mm, dy=10mm

Cursor:

ABM1 = 16.5147 dB A/m

BWC Factor = -0.206004 dB

Location: 0, 0, 363.7 mm



0 dB = 1.00A/m

Test Laboratory: Compliance Certification Services
File Name: [ch 1013 RC3 SO3 8k Enhanced Low.da4](#)

DUT: HCT Dual Band phone; Type: PN-819; Serial: N/A
Program Name: HAC_TCoil_WD_Emission

Communication System: CDMA; Frequency: 824.7 MHz; Duty Cycle: 1:1

Medium parameters used: $\sigma = 0$ mho/m, $\epsilon_r = 1$; $\rho = 1$ kg/m³

Phantom section: AMB with Coil Section

DASY4 Configuration:

- Probe: AM1DV2 - 1012; ; Calibrated: 4/18/2006
- Sensor-Surface: 0mm (Fix Surface)
- Electronics: DAE4 SN558; Calibrated: 1/20/2006
- Phantom: HAC Test Arch with Coil; Type: SD HAC P01 BA; Serial: 100x
- Measurement SW: DASY4, V4.7 Build 44; Postprocessing SW: SEMCAD, V1.8 Build 171

Scans/z (axial) rough 50 x 50/ABM Interpolated Signal(x,y,z) (61x61x1):

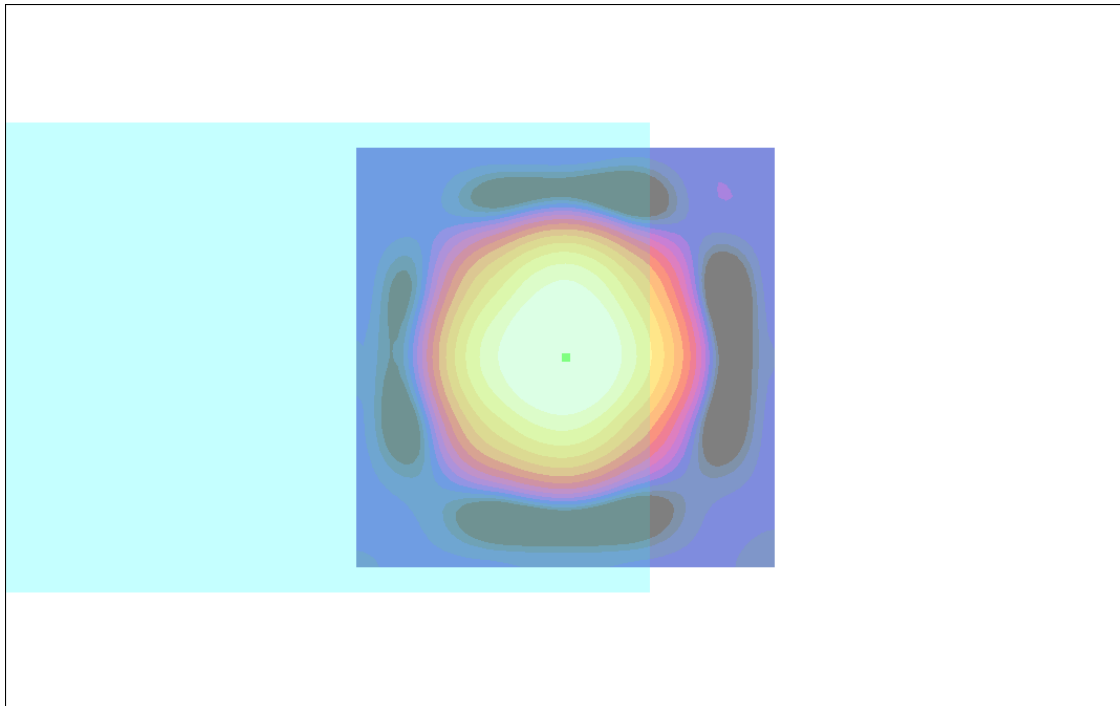
Measurement grid: dx=10mm, dy=10mm

Cursor:

ABM1 = 13.4406 dB A/m

BWC Factor = -0.206004 dB

Location: 0, 0, 363.7 mm



0 dB = 1.00A/m

Test Laboratory: Compliance Certification Services
File Name: [ch 384 RC3 SO3 8k Enhanced Low.da4](#)

DUT: HCT Dual Band phone; Type: PN-819; Serial: N/A
Program Name: HAC_TCoil_WD_Emission

Communication System: CDMA; Frequency: 836.52 MHz; Duty Cycle: 1:1

Medium parameters used: $\sigma = 0$ mho/m, $\epsilon_r = 1$; $\rho = 1$ kg/m³

Phantom section: AMB with Coil Section

DASY4 Configuration:

- Probe: AM1DV2 - 1012; ; Calibrated: 4/18/2006
- Sensor-Surface: 0mm (Fix Surface)
- Electronics: DAE4 SN558; Calibrated: 1/20/2006
- Phantom: HAC Test Arch with Coil; Type: SD HAC P01 BA; Serial: 100x
- Measurement SW: DASY4, V4.7 Build 44; Postprocessing SW: SEMCAD, V1.8 Build 171

Scans/z (axial) rough 50 x 50/ABM Interpolated Signal(x,y,z) (61x61x1):

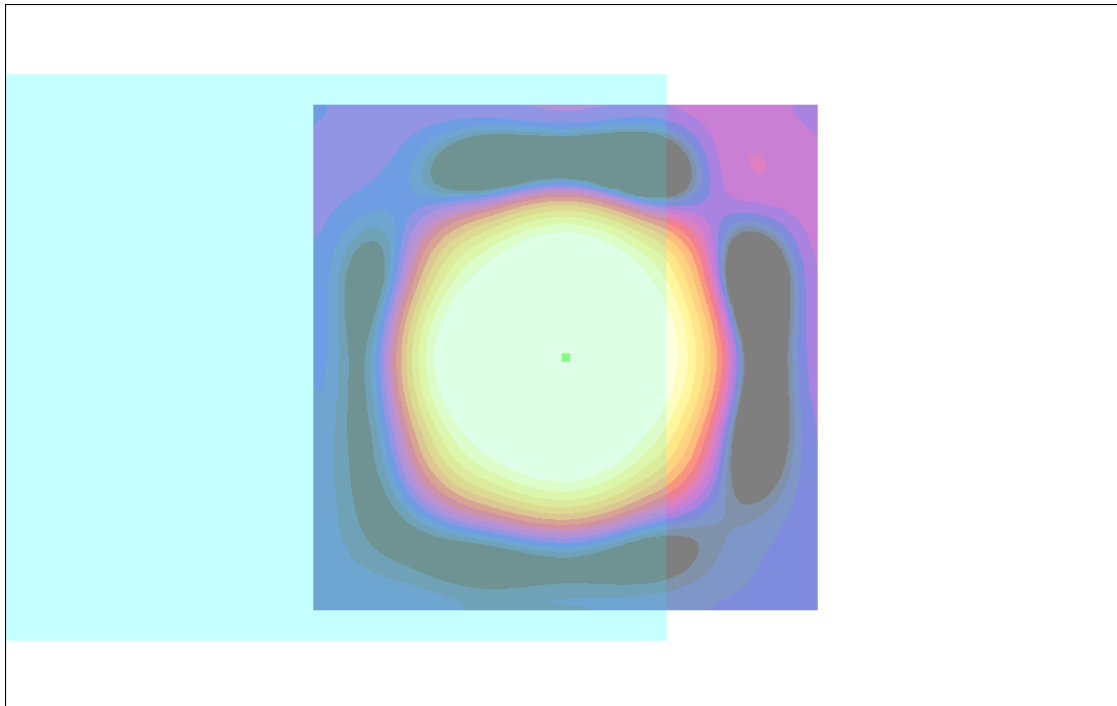
Measurement grid: dx=10mm, dy=10mm

Cursor:

ABM1 = 11.9237 dB A/m

BWC Factor = -0.206004 dB

Location: 0, 0, 363.7 mm



0 dB = 1.00A/m

Test Laboratory: Compliance Certification Services
File Name: [ch 777 RC3 SO3 8k Enhanced Low.da4](#)

DUT: HCT Dual Band phone; Type: PN-819; Serial: N/A
Program Name: HAC_TCoil_WD_Emission

Communication System: CDMA; Frequency: 848.31 MHz; Duty Cycle: 1:1

Medium parameters used: $\sigma = 0$ mho/m, $\epsilon_r = 1$; $\rho = 1$ kg/m³

Phantom section: AMB with Coil Section

DASY4 Configuration:

- Probe: AM1DV2 - 1012; ; Calibrated: 4/18/2006
- Sensor-Surface: 0mm (Fix Surface)
- Electronics: DAE4 SN558; Calibrated: 1/20/2006
- Phantom: HAC Test Arch with Coil; Type: SD HAC P01 BA; Serial: 100x
- Measurement SW: DASY4, V4.7 Build 44; Postprocessing SW: SEMCAD, V1.8 Build 171

Scans/z (axial) rough 50 x 50/ABM Interpolated Signal(x,y,z) (61x61x1):

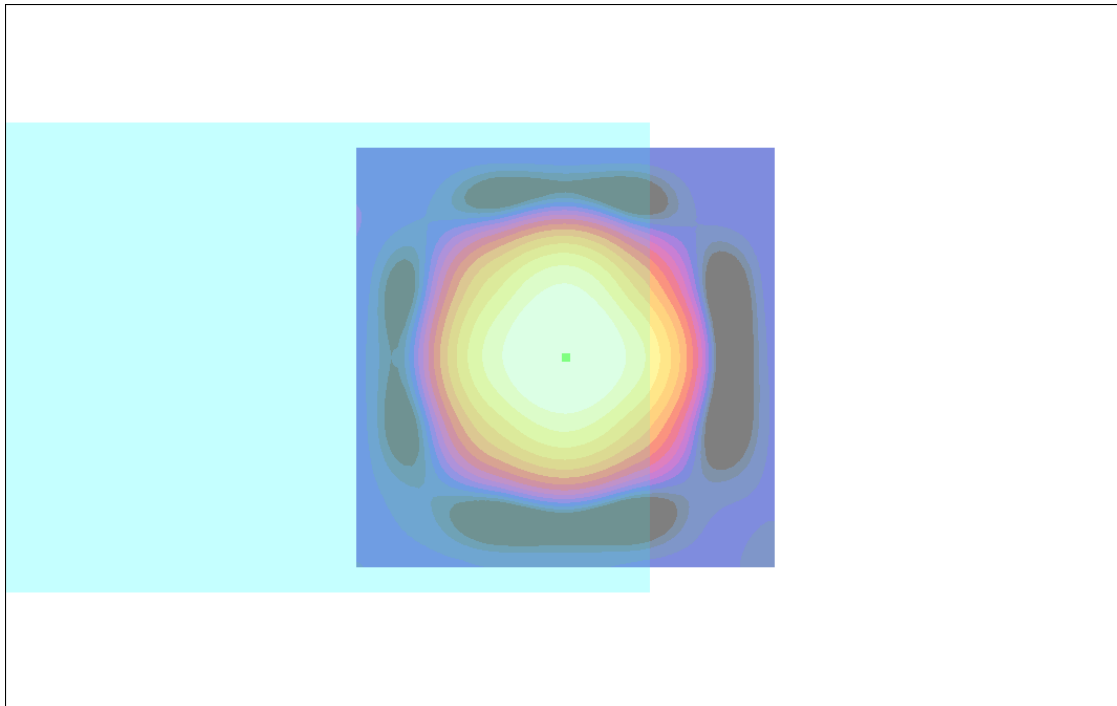
Measurement grid: dx=10mm, dy=10mm

Cursor:

ABM1 = 12.4882 dB A/m

BWC Factor = -0.206004 dB

Location: 0, 0, 363.7 mm



0 dB = 1.00A/m

Test Laboratory: Compliance Certification Services
File Name: [ch 384 RC43 SO3 8K Enhanced Low.da4](#)

DUT: HCT Dual Band phone; Type: PN-819; Serial: N/A
Program Name: HAC_TCoil_WD_Emission

Communication System: CDMA; Frequency: 836.52 MHz; Duty Cycle: 1:1

Medium parameters used: $\sigma = 0$ mho/m, $\epsilon_r = 1$; $\rho = 1$ kg/m³

Phantom section: AMB with Coil Section

DASY4 Configuration:

- Probe: AM1DV2 - 1012; ; Calibrated: 4/18/2006
- Sensor-Surface: 0mm (Fix Surface)
- Electronics: DAE4 SN558; Calibrated: 1/20/2006
- Phantom: HAC Test Arch with Coil; Type: SD HAC P01 BA; Serial: 100x
- Measurement SW: DASY4, V4.7 Build 44; Postprocessing SW: SEMCAD, V1.8 Build 171

Scans/z (axial) rough 50 x 50/ABM Interpolated Signal(x,y,z) (61x61x1):

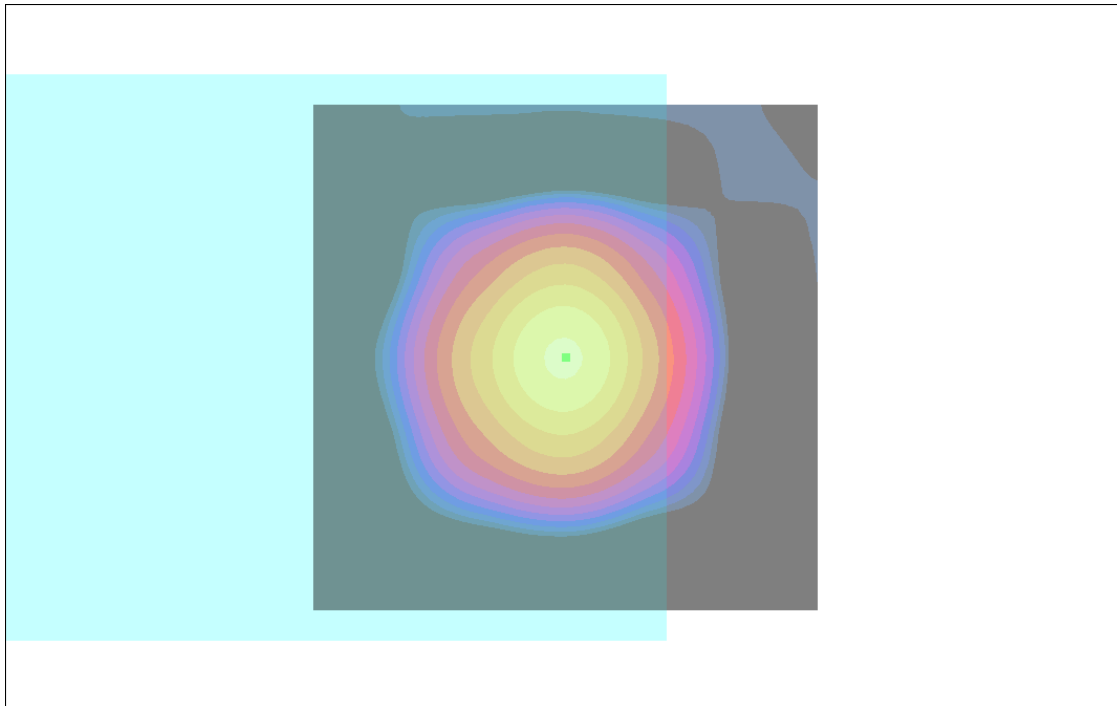
Measurement grid: dx=10mm, dy=10mm

Cursor:

ABM1 = 15.2567 dB A/m

BWC Factor = 0.165018 dB

Location: 0, 0, 363.7 mm



0 dB = 1.00A/m

Test Laboratory: Compliance Certification Services

File Name: [ch 384 - RC54 SO17 13K Low.da4](#)

DUT: HCT Dual Band phone; Type: PN-819; Serial: N/A

Program Name: HAC_TCoil_WD_Emission

Communication System: CDMA; Frequency: 836.52 MHz; Duty Cycle: 1:1

Medium parameters used: $\sigma = 0$ mho/m, $\epsilon_r = 1$; $\rho = 1$ kg/m³

Phantom section: AMB with Coil Section

DASY4 Configuration:

- Probe: AM1DV2 - 1012; ; Calibrated: 4/18/2006
- Sensor-Surface: 0mm (Fix Surface)
- Electronics: DAE4 SN558; Calibrated: 1/20/2006
- Phantom: HAC Test Arch with Coil; Type: SD HAC P01 BA; Serial: 100x
- Measurement SW: DASY4, V4.7 Build 44; Postprocessing SW: SEMCAD, V1.8 Build 171

Scans/z (axial) rough 50 x 50/ABM Interpolated Signal(x,y,z) (61x61x1):

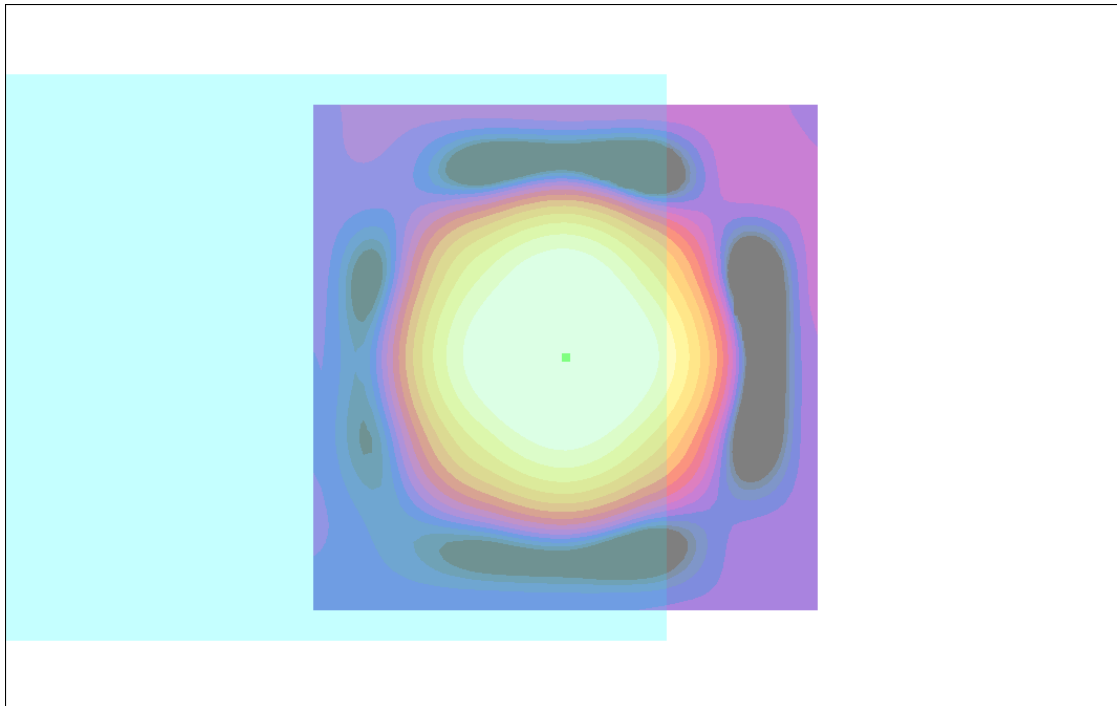
Measurement grid: dx=10mm, dy=10mm

Cursor:

ABM1 = 16.5038 dB A/m

BWC Factor = -0.206004 dB

Location: 0, 0, 363.7 mm



0 dB = 1.00A/m

Test Laboratory: Compliance Certification Services

File Name: [ch 384 RC3 SO3 8k Enhanced Low - side open.da4](#)

DUT: HCT Dual Band phone; Type: PN-819; Serial: N/A

Program Name: HAC_TCoil_WD_Emission

Communication System: CDMA; Frequency: 836.52 MHz; Duty Cycle: 1:1

Medium parameters used: $\sigma = 0$ mho/m, $\epsilon_r = 1$; $\rho = 1$ kg/m³

Phantom section: AMB with Coil Section

DASY4 Configuration:

- Probe: AM1DV2 - 1012; ; Calibrated: 4/18/2006

- Sensor-Surface: 0mm (Fix Surface)

- Electronics: DAE4 SN558; Calibrated: 1/20/2006

- Phantom: HAC Test Arch with Coil; Type: SD HAC P01 BA; Serial: 100x

- Measurement SW: DASY4, V4.7 Build 44; Postprocessing SW: SEMCAD, V1.8 Build 171

Scans/z (axial) rough 50 x 50/ABM Interpolated Signal(x,y,z) (61x61x1):

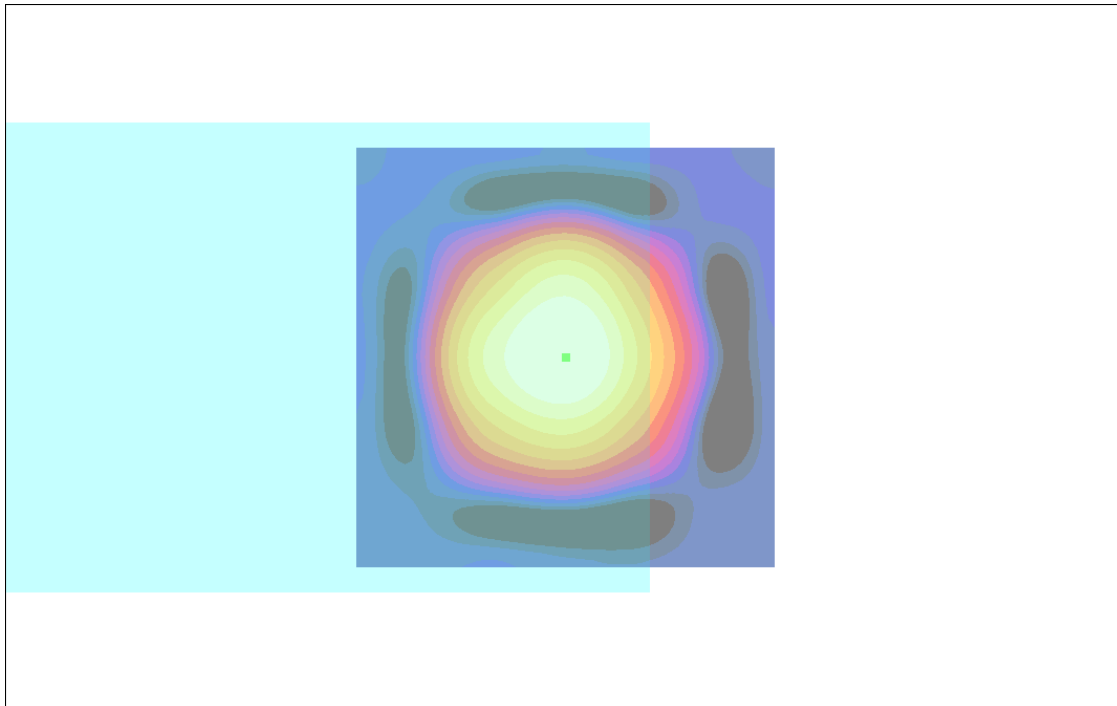
Measurement grid: dx=10mm, dy=10mm

Cursor:

ABM1 = 11.7058 dB A/m

BWC Factor = -0.206004 dB

Location: 0, 0, 363.7 mm



0 dB = 1.00A/m

Test Laboratory: Compliance Certification Services
File Name: [ch 600 RC1 SO3 8k Enhanced Low.da4](#)

DUT: HCT Dual Band phone; Type: PN-819; Serial: N/A
Program Name: HAC_TCoil_WD_Emission

Communication System: CDMA; Frequency: 1880 MHz; Duty Cycle: 1:1

Medium parameters used: $\sigma = 0$ mho/m, $\epsilon_r = 1$; $\rho = 1$ kg/m³

Phantom section: AMB with Coil Section

DASY4 Configuration:

- Probe: AM1DV2 - 1012; ; Calibrated: 4/18/2006
- Sensor-Surface: 0mm (Fix Surface)
- Electronics: DAE4 SN558; Calibrated: 1/20/2006
- Phantom: HAC Test Arch with Coil; Type: SD HAC P01 BA; Serial: 100x
- Measurement SW: DASY4, V4.7 Build 44; Postprocessing SW: SEMCAD, V1.8 Build 171

Scans/z (axial) rough 50 x 50/ABM Interpolated Signal(x,y,z) (61x61x1):

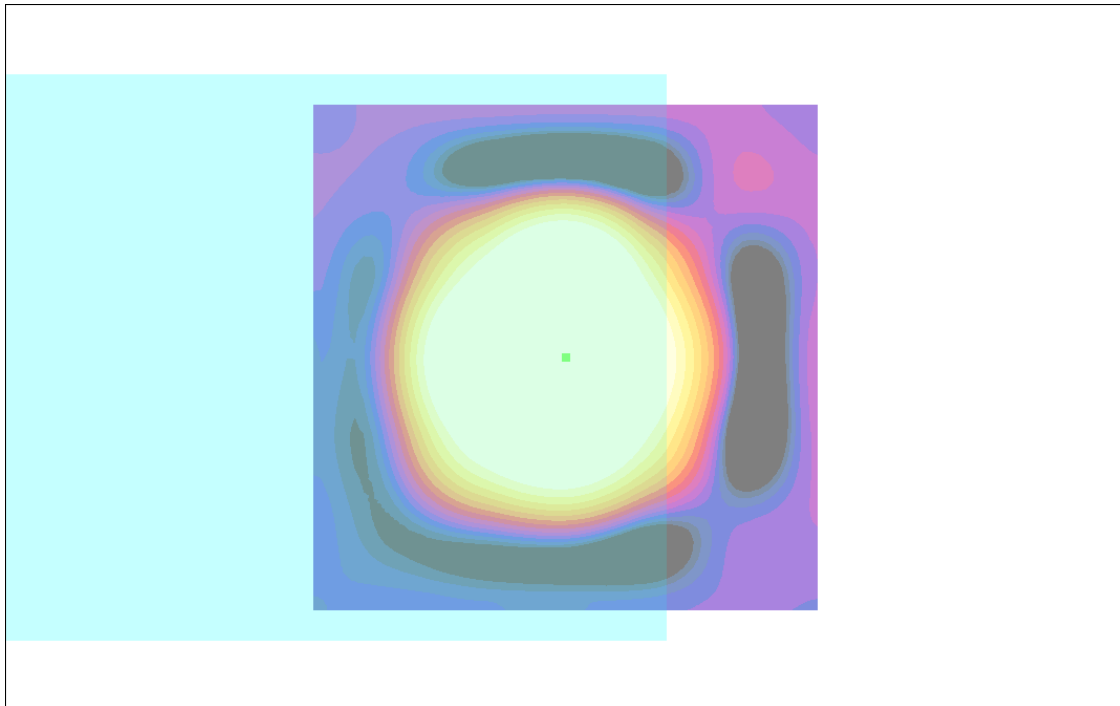
Measurement grid: dx=10mm, dy=10mm

Cursor:

ABM1 = 13.1435 dB A/m

BWC Factor = -0.206004 dB

Location: 0, 0, 363.7 mm



0 dB = 1.00A/m

Test Laboratory: Compliance Certification Services

File Name: [ch-600 RC2 SO17 13k Low.da4](#)

DUT: HCT Dual Band phone; Type: PN-819; Serial: N/A

Program Name: HAC_TCoil_WD_Emission

Communication System: CDMA; Frequency: 1880 MHz; Duty Cycle: 1:1

Medium parameters used: $\sigma = 0$ mho/m, $\epsilon_r = 1$; $\rho = 1$ kg/m³

Phantom section: AMB with Coil Section

DASY4 Configuration:

- Probe: AM1DV2 - 1012; ; Calibrated: 4/18/2006
- Sensor-Surface: 0mm (Fix Surface)
- Electronics: DAE4 SN558; Calibrated: 1/20/2006
- Phantom: HAC Test Arch with Coil; Type: SD HAC P01 BA; Serial: 100x
- Measurement SW: DASY4, V4.7 Build 44; Postprocessing SW: SEMCAD, V1.8 Build 171

Scans/z (axial) rough 50 x 50/ABM Interpolated Signal(x,y,z) (61x61x1):

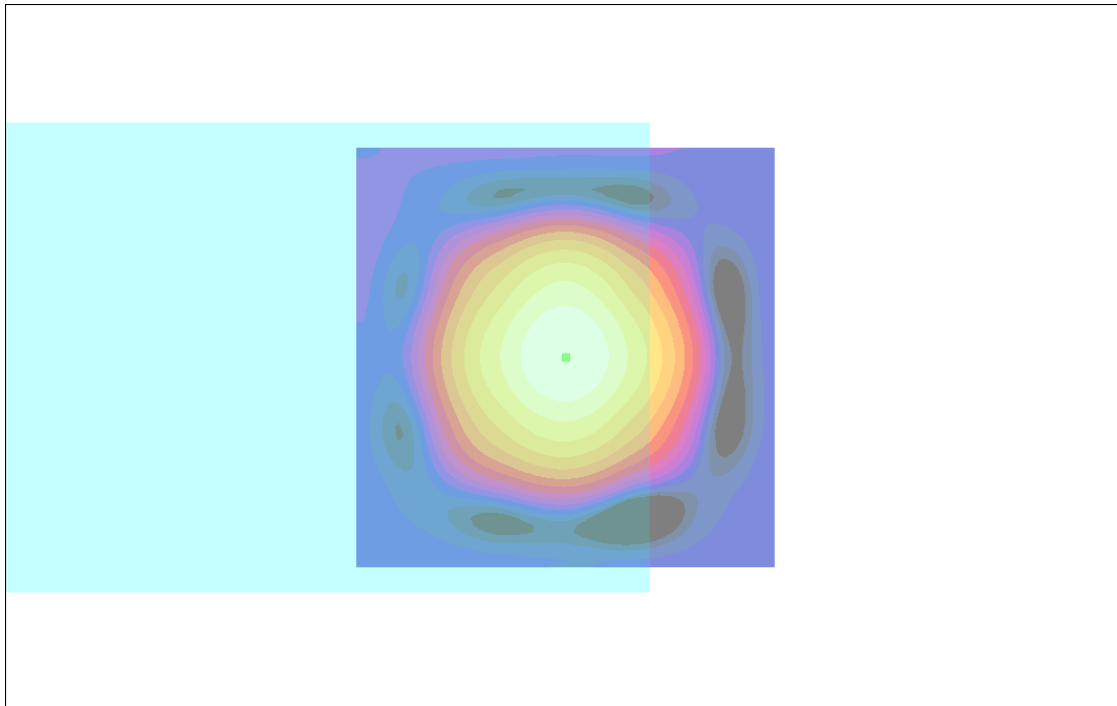
Measurement grid: dx=10mm, dy=10mm

Cursor:

ABM1 = 15.4471 dB A/m

BWC Factor = -0.206004 dB

Location: 0, 0, 363.7 mm



0 dB = 1.00A/m

Test Laboratory: Compliance Certification Services
File Name: [ch 600 RC3 SO3 8K Enhanced Low.da4](#)

DUT: HCT Dual Band phone; Type: PN-819; Serial: N/A
Program Name: HAC_TCoil_WD_Emission

Communication System: CDMA; Frequency: 1880 MHz; Duty Cycle: 1:1

Medium parameters used: $\sigma = 0$ mho/m, $\epsilon_r = 1$; $\rho = 1$ kg/m³

Phantom section: AMB with Coil Section

DASY4 Configuration:

- Probe: AM1DV2 - 1012; ; Calibrated: 4/18/2006
- Sensor-Surface: 0mm (Fix Surface)
- Electronics: DAE4 SN558; Calibrated: 1/20/2006
- Phantom: HAC Test Arch with Coil; Type: SD HAC P01 BA; Serial: 100x
- Measurement SW: DASY4, V4.7 Build 44; Postprocessing SW: SEMCAD, V1.8 Build 171

Scans/z (axial) rough 50 x 50/ABM Interpolated Signal(x,y,z) (61x61x1):

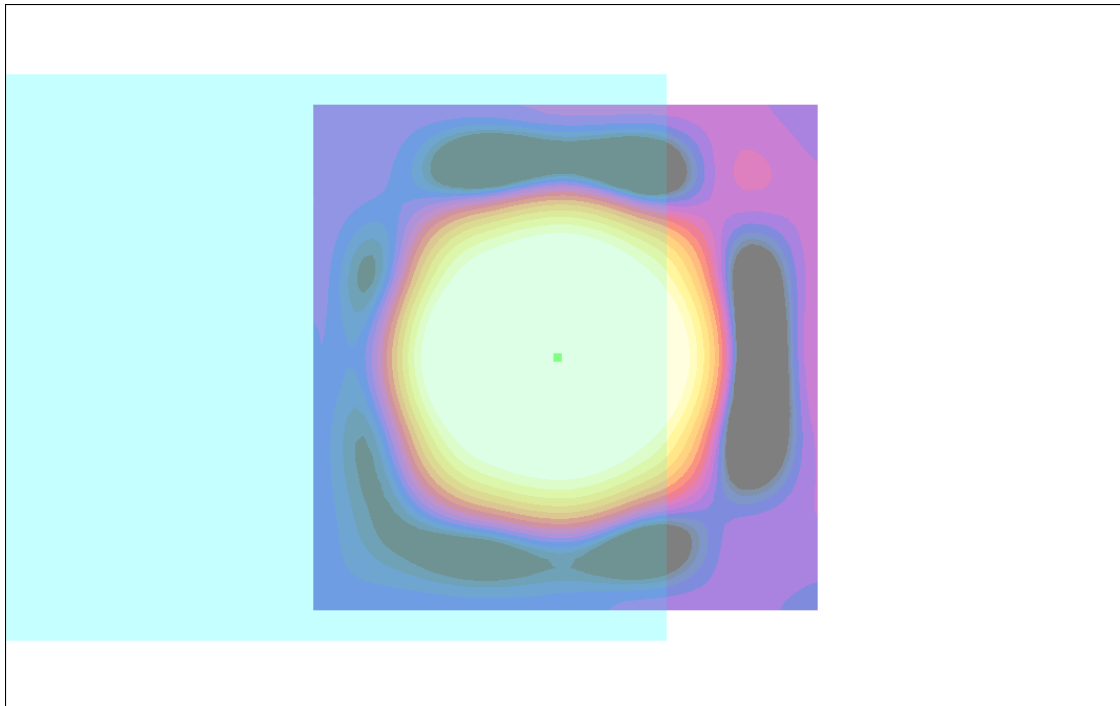
Measurement grid: dx=10mm, dy=10mm

Cursor:

ABM1 = 11.9948 dB A/m

BWC Factor = -0.206004 dB

Location: 0.8, 0, 363.7 mm



0 dB = 1.00A/m

Test Laboratory: Compliance Certification Services
File Name: [ch 600 RC43 SO3 8K Enhanced Low.da4](#)

DUT: HCT Dual Band phone; Type: PN-819; Serial: N/A
Program Name: HAC_TCoil_WD_Emission

Communication System: CDMA; Frequency: 1880 MHz; Duty Cycle: 1:1

Medium parameters used: $\sigma = 0$ mho/m, $\epsilon_r = 1$; $\rho = 1$ kg/m³

Phantom section: AMB with Coil Section

DASY4 Configuration:

- Probe: AM1DV2 - 1012; ; Calibrated: 4/18/2006
- Sensor-Surface: 0mm (Fix Surface)
- Electronics: DAE4 SN558; Calibrated: 1/20/2006
- Phantom: HAC Test Arch with Coil; Type: SD HAC P01 BA; Serial: 100x
- Measurement SW: DASY4, V4.7 Build 44; Postprocessing SW: SEMCAD, V1.8 Build 171

Scans/z (axial) rough 50 x 50/ABM Interpolated Signal(x,y,z) (61x61x1):

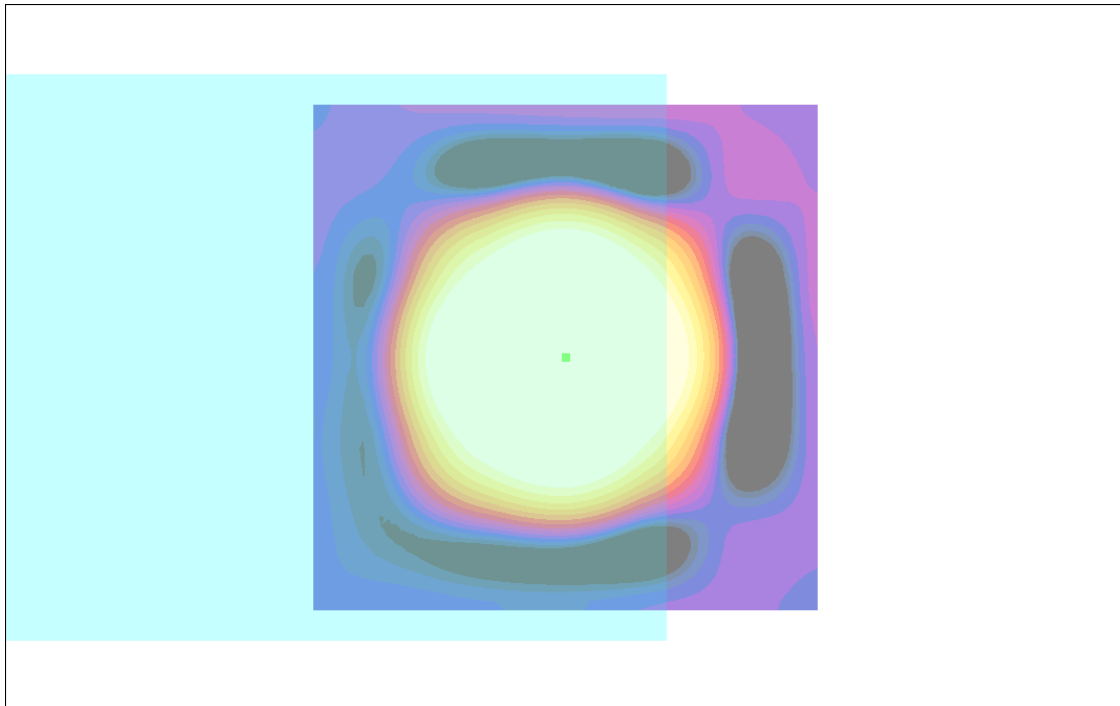
Measurement grid: dx=10mm, dy=10mm

Cursor:

ABM1 = 12.5845 dB A/m

BWC Factor = -0.204999 dB

Location: 0, 0, 363.7 mm



0 dB = 1.00A/m

Test Laboratory: Compliance Certification Services

File Name: [ch 25 RC54 SO17 13k Low.da4](#)

DUT: HCT Dual Band phone; Type: PN-819; Serial: N/A

Program Name: HAC_TCoil_WD_Emission

Communication System: CDMA; Frequency: 1851.25 MHz; Duty Cycle: 1:1

Medium parameters used: $\sigma = 0$ mho/m, $\epsilon_r = 1$; $\rho = 1$ kg/m³

Phantom section: AMB with Coil Section

DASY4 Configuration:

- Probe: AM1DV2 - 1012; ; Calibrated: 4/18/2006
- Sensor-Surface: 0mm (Fix Surface)
- Electronics: DAE4 SN558; Calibrated: 1/20/2006
- Phantom: HAC Test Arch with Coil; Type: SD HAC P01 BA; Serial: 100x
- Measurement SW: DASY4, V4.7 Build 44; Postprocessing SW: SEMCAD, V1.8 Build 171

Scans/z (axial) rough 50 x 50/ABM Interpolated Signal(x,y,z) (61x61x1):

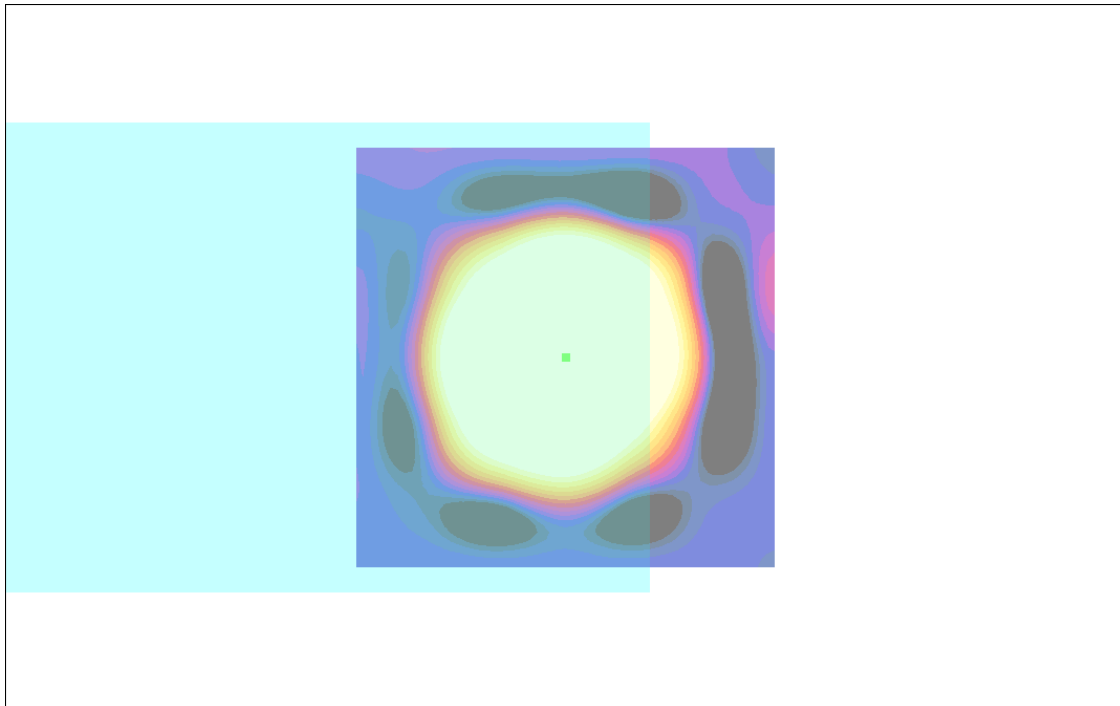
Measurement grid: dx=10mm, dy=10mm

Cursor:

ABM1 = 15.7673 dB A/m

BWC Factor = -0.206004 dB

Location: 0, 0, 363.7 mm



0 dB = 1.00A/m

Test Laboratory: Compliance Certification Services

File Name: [ch-600 RC54 SO17 13k Low.da4](#)

DUT: HCT Dual Band phone; Type: PN-819; Serial: N/A

Program Name: HAC_TCoil_WD_Emission

Communication System: CDMA; Frequency: 1880 MHz; Duty Cycle: 1:1

Medium parameters used: $\sigma = 0$ mho/m, $\epsilon_r = 1$; $\rho = 1$ kg/m³

Phantom section: AMB with Coil Section

DASY4 Configuration:

- Probe: AM1DV2 - 1012; ; Calibrated: 4/18/2006
- Sensor-Surface: 0mm (Fix Surface)
- Electronics: DAE4 SN558; Calibrated: 1/20/2006
- Phantom: HAC Test Arch with Coil; Type: SD HAC P01 BA; Serial: 100x
- Measurement SW: DASY4, V4.7 Build 44; Postprocessing SW: SEMCAD, V1.8 Build 171

Scans/z (axial) rough 50 x 50/ABM Interpolated Signal(x,y,z) (61x61x1):

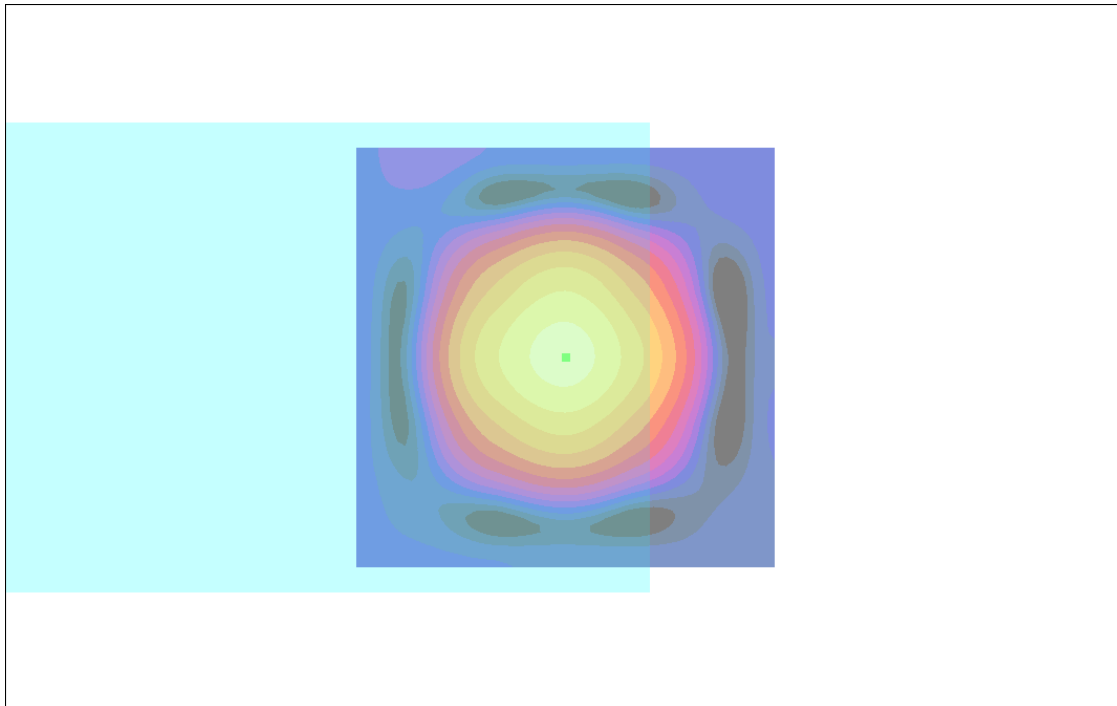
Measurement grid: dx=10mm, dy=10mm

Cursor:

ABM1 = 14.9984 dB A/m

BWC Factor = -0.204999 dB

Location: 0, 0, 363.7 mm



0 dB = 1.00A/m

Test Laboratory: Compliance Certification Services

File Name: [ch 1175 RC54 SO17 13k Low.da4](#)

DUT: HCT Dual Band phone; Type: PN-819; Serial: N/A

Program Name: HAC_TCoil_WD_Emission

Communication System: CDMA; Frequency: 1908.75 MHz; Duty Cycle: 1:1

Medium parameters used: $\sigma = 0$ mho/m, $\epsilon_r = 1$; $\rho = 1$ kg/m³

Phantom section: AMB with Coil Section

DASY4 Configuration:

- Probe: AM1DV2 - 1012; ; Calibrated: 4/18/2006

- Sensor-Surface: 0mm (Fix Surface)

- Electronics: DAE4 SN558; Calibrated: 1/20/2006

- Phantom: HAC Test Arch with Coil; Type: SD HAC P01 BA; Serial: 100x

- Measurement SW: DASY4, V4.7 Build 44; Postprocessing SW: SEMCAD, V1.8 Build 171

Scans/z (axial) rough 50 x 50/ABM Interpolated Signal(x,y,z) (61x61x1):

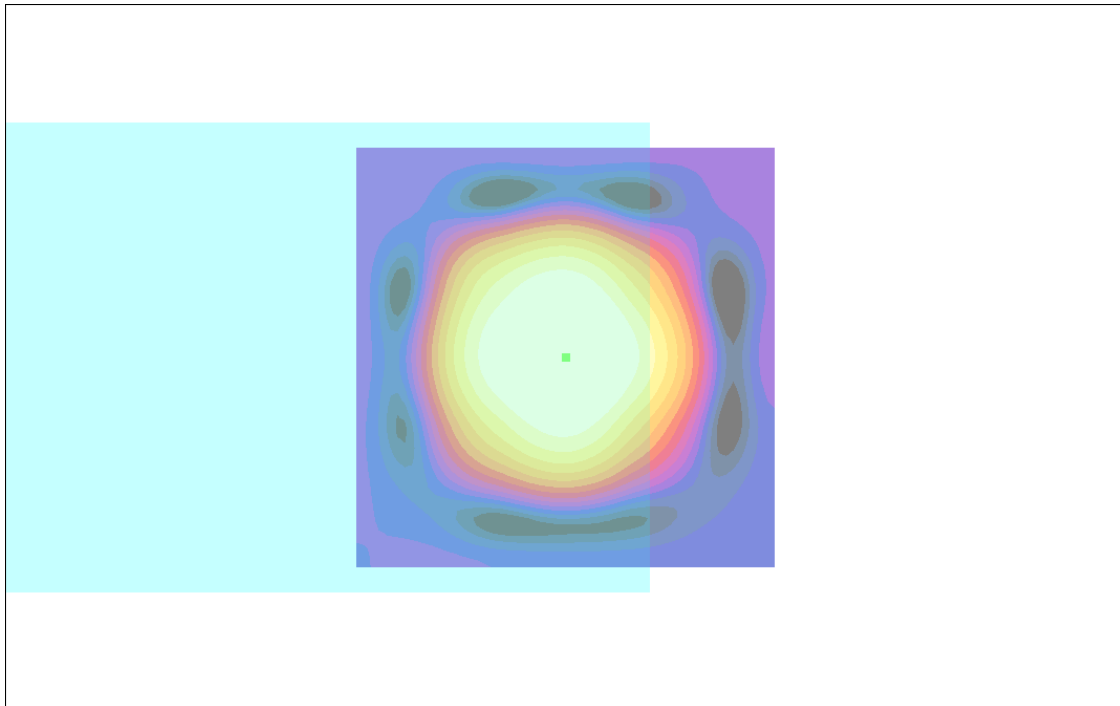
Measurement grid: dx=10mm, dy=10mm

Cursor:

ABM1 = 15.4788 dB A/m

BWC Factor = -0.206004 dB

Location: 0, 0, 363.7 mm



0 dB = 1.00A/m

Test Laboratory: Compliance Certification Services

File Name: [ch-600 RC54 SO17 13k Low - side open.da4](#)

DUT: HCT Dual Band phone; Type: PN-819; Serial: N/A

Program Name: HAC_TCoil_WD_Emission

Communication System: CDMA; Frequency: 1880 MHz; Duty Cycle: 1:1

Medium parameters used: $\sigma = 0$ mho/m, $\epsilon_r = 1$; $\rho = 1$ kg/m³

Phantom section: AMB with Coil Section

DASY4 Configuration:

- Probe: AM1DV2 - 1012; ; Calibrated: 4/18/2006

- Sensor-Surface: 0mm (Fix Surface)

- Electronics: DAE4 SN558; Calibrated: 1/20/2006

- Phantom: HAC Test Arch with Coil; Type: SD HAC P01 BA; Serial: 100x

- Measurement SW: DASY4, V4.7 Build 44; Postprocessing SW: SEMCAD, V1.8 Build 171

Scans/z (axial) rough 50 x 50/ABM Interpolated Signal(x,y,z) (61x61x1):

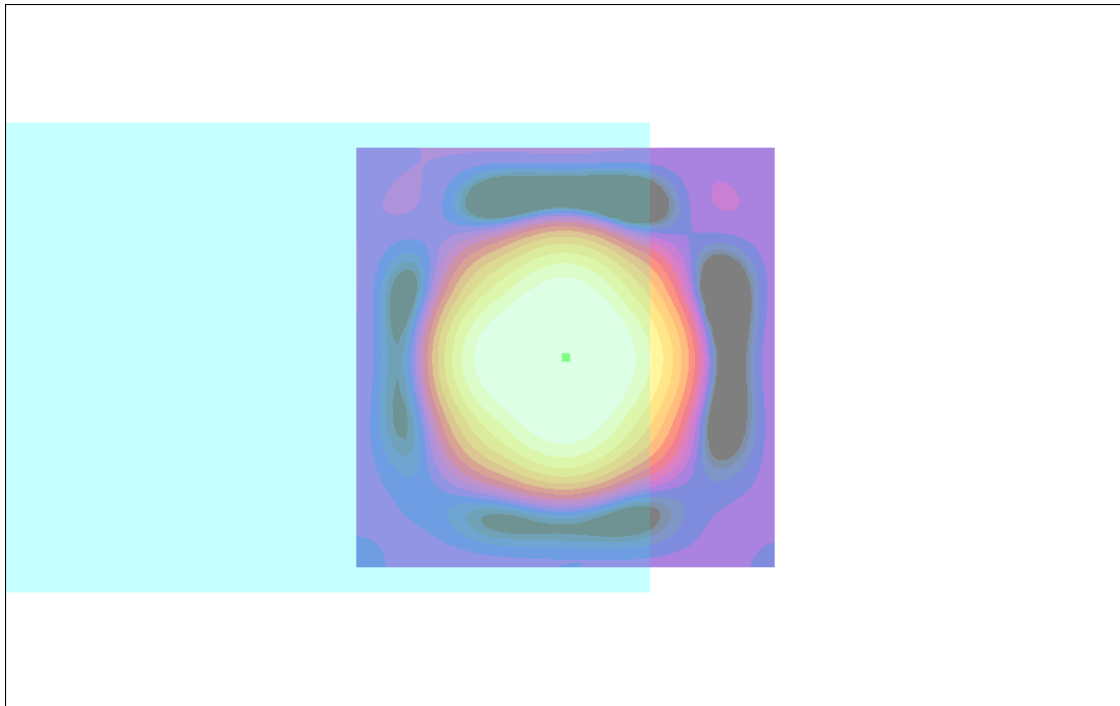
Measurement grid: dx=10mm, dy=10mm

Cursor:

ABM1 = 16.1399 dB A/m

BWC Factor = -0.206004 dB

Location: 0, 0, 363.7 mm



0 dB = 1.00A/m